



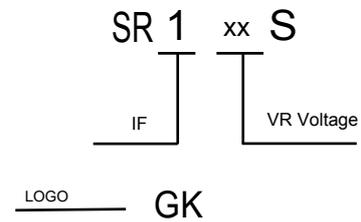
## FEATURES

- \* Low forward voltage drop
- \* High current capability
- \* High reliability
- \* High surge current capability
- \* Epitaxial construction

## MECHANICAL DATA

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Lead: Axial leads, solderable per MIL-STD-202, method 208 guaranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any

VOLTAGE RANGE  
20 to 100 Volts  
CURRENT  
1.0 Ampere



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

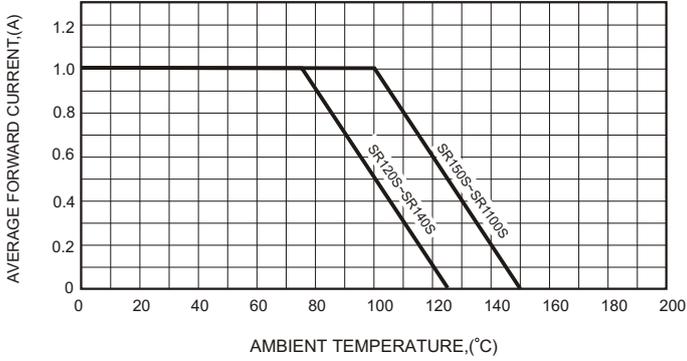
TYPE NUMBER	SR120S	SR130S	SR140S	SR150S	SR160S	SR180S	SR1100S	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	100	V
Maximum RMS Voltage	14	21	28	35	42	56	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	100	V
Maximum Average Forward Rectified Current See Fig. 1	1.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	30							A
Maximum Instantaneous Forward Voltage at 1.0A	0.55		0.70		0.85			V
Maximum DC Reverse Current Ta=25°C	0.2							mA
at Rated DC Blocking Voltage Ta=100°C	10							mA
Typical Junction Capacitance (Note1)	110							pF
Typical Thermal Resistance R JA (Note 2)	50							°C/W
Operating Temperature Range Tj	-65 — +125			-65 — +150				°C
Storage Temperature Range Tstg	-65 — +150							°C

**NOTES:**

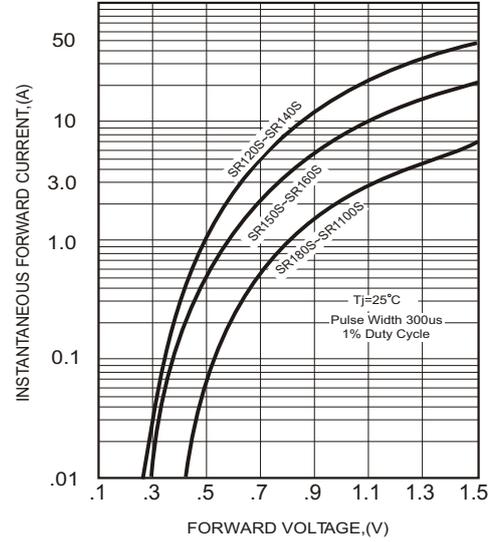
1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Ambient Vertical PC Board Mounting 0.5"(12.7mm) Lead Length.

**RATING AND CHARACTERISTIC CURVES**

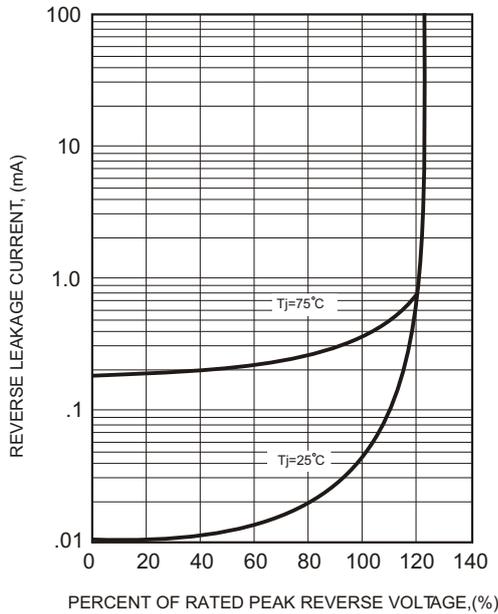
**FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE**



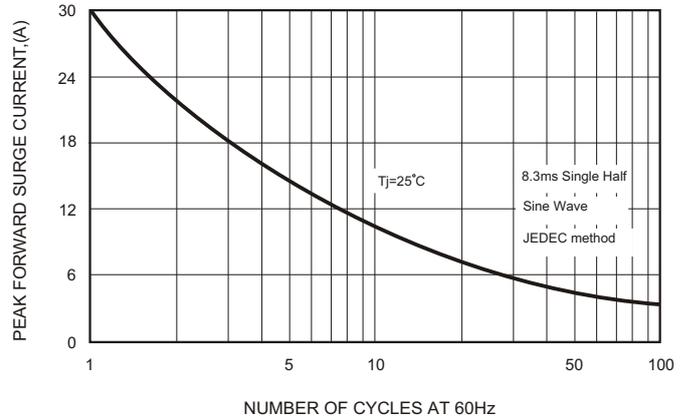
**FIG.2-TYPICAL FORWARD CHARACTERISTICS**



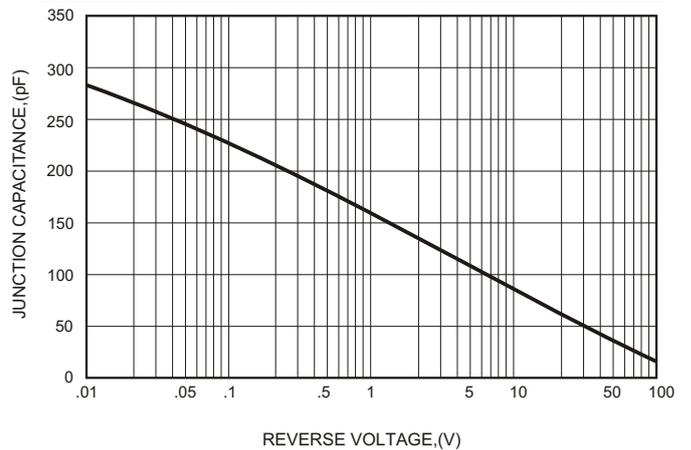
**FIG.6 - TYPICAL REVERSE CHARACTERISTICS**



**FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



**FIG.5-TYPICAL JUNCTION CAPACITANCE**



Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

